Hubbell-Acme Electric N56 W13385 Silver Spring Drive, Menomonee Falls WI 53051

Declaration of Conformity to RoHS 3

July 23, 2024

Hubbell Incorporated (Delaware), ACME Division is the supplier to Automation Direct for the ACME part number(s) in the table below.

RoHS compliance is defined as meeting the applicable provisions of the **European Union Directive 2011/65/EU (RoHS) and Directive 2015/863/EU, as amended.** The following table lists the restricted materials and their respective allowable limits.[1]

RoHS Restricted Substance	Allowable Limit
Cadmium and its compounds	100 ppm (0.01 weight %)
Mercury and its compounds	1000 ppm (0.1 weight %)
Hexavalent chromium and its compounds	1000 ppm (0.1 weight %)
Lead and its compounds	1000 ppm (0.1 weight %)
Polybrominated biphenyls (PBB)	1000 ppm (0.1 weight %)
Polybrominated diphenyl ethers (PBDE)*	1000 ppm (0.1 weight %)
Bis(2-ethylhexyl) phthalate (DEHP)	1000 ppm (0.1 weight %)
Butyl benzyl phthalate (BBP)	1000 ppm (0.1 weight %)
Dibutyl phthalate (DBP)	1000 ppm (0.1 weight %)
Diisobutyl phthalate (DIBP)	1000 ppm (0.1 weight %)

*note including Deca-BDE

[1]For parts/products that exceed the allowable limits per homogeneous material level, certain exemptions are permitted as defined and identified on the following pages in order to determine conformity to EU Directive 2011/65/EU **(**RoHS) and EU Directive 2015/863/EU.
For additional information, see http://europa.eu.int/comm/environment/waste/weee_index.htm)

RoHS Compliant – Yes or No

Part Numbers	HUBBELL Inc. ACME Division Part Numbers	Yes	No	Exemption Number(s) (enter "none" if no exemptions used)
T181047	T181047	X		none
T181048	T181048	X		none
T181049	T181049	X		none
T181050	T181050	X		none
T181051	T181051	X		none
T181052	T181052	X		none
T111683	T111683	X		none
T111684	T111684	X		none
T111685	T111685	X		none
T111686	T111686	X		none
T111687	T111687	X		none
T181055	T181055	X		none

T181056	T181056	X		none
T181057	T181057	X		none
T181058	T181058	X		none
T181059	T181059	X		none
T113073	T113073	X		none
T113074	T113074	X		none
T113075	T113075	X		none
T113076	T113076	X		none
T113077	T113077	X		none
T181062	T181062	X		none
T181063	T181063	X		none
T181064	T181064	X		none
T181065	T181065	X		none
T181066	T181066	X		none
T137920	T137920	X		none
T137921	T137921	X		none
T137922	T137922	X		none
T137923	T137923	X		none
T137924	T137924	X		none
T153005	T153005	X		none
T153006	T153006	X		none
T253007S	T253007S	X		none
T253008S	T253008S	X		none
T253009S	T253009S	X		none
T253010S	T253010S	X		none
T253011S	T253011S	X		none
T253012S	T253012S	X		none
T2530134S	T2530134S	X		none
T2530144S	T2530144S	X		none
T2535153S	T2535153S	X		none
T2535163S	T2535163S	X		none
T2535173S	T2535173S	X		none
T2535183S	T2535183S	X		none
T253108S	T253108S	X		none
T253109S	T253109S	X		none
T253110S	T253110S	X		none
T253111S	T253111S	X		none
T253112S	T253112S	X		none
T2531131S	T2531131S	X		none
T2531141S	T2531141S	X		none

T2536151S	T2536151S	X		none
T2536161S	T2536161S	X		none
T2536171S	T2536171S	X		none
T279740S	T279740S	X		none
T279741S	T279741S	X		none
T279742S	T279742S	X		none
T279743S	T279743S	X		none
T279744S	T279744S	X		none
T279745S	T279745S	X		none
T279746S	T279746S	X		none
TF217437S	TF217437S	X		none
TF217439S	TF217439S	X		none
TF249873S	TF249873S	X		none
TF252520S	TF252520S	X		none
TF252794S	TF252794S	X		none
TF252795S	TF252795S	X		none

Any non-conformance subsequently determined will be immediately reported to Automation Direct.

Signature: *Antonio Rowland* Date: 7/23/2024

Name: Antonio Rowland Phone: (800) -334-5214

Title: Technical Service e-mail: arowland@hubbellacme.com

List of Permitted Exemptions

1 MERCURY in single capped (compact) fluorescent lamps not exceeding:

1a For general lighting purposes < 30 W: 5 mg per burner.
Expired December 31, 2011
After December 31, 2011: 3.5 mg per burner
After December 31, 2012: 2.5 mg per burner

1b For general lighting purposes ≥ 30 W and < 50 W: 5 mg per burner
Expired December 31, 2011
After December 31, 2011: 3.5 mg per burner

1c For general lighting purposes ≥ 50 W and < 150 W: 5 mg per burner

1d For general lighting purposes ≥ 150 W: 15 mg per burner

1e For general lighting purposes with circular or square structural shape and tube diameter ≤ 17 mm. *No limitation of use until December 31, 2011*
After December 31, 2011: 7 mg per burner

1f For special purposes: 5 mg per burner

2a MERCURY in double-capped linear fluorescent lamps for general lighting purposes not exceeding:

2a1 Tri-band phosphor with normal lifetime and a tube diameter < 9 mm (T2):
5 mg per lamp. *Expired December 31, 2011*
After December 31, 2011: 4 mg per lamp

2a2 Tri-band phosphor with normal lifetime and a tube diameter ≥ 9 mm and ≤ 17 mm (T5): 5 mg per lamp. *Expired December 31, 2011*
After December 31, 2011: 3 mg per lamp

2a3 Tri-band phosphor with normal lifetime and a tube diameter > 17 mm and ≤ 28 mm (T8): 5 mg per lamp. *Expired December 31, 2011*
After December 31, 2011: 3.5 mg per lamp

2a4 Tri-band phosphor with normal lifetime and a tube diameter > 28 mm (T12): 5 mg per lamp. *Expires on December 31, 2012*
After December 31, 2012: 3.5 mg per lamp

2a5 Tri-band phosphor with long lifetime (≥ 25 000 h): 8 mg per lamp
Expired December 31, 2011. After December 31, 2011: 5 mg per lamp

2b MERCURY in other fluorescent lamps not exceeding:

2b1 ~~Linear halophosphate lamps with tube > 28 mm (T10 and T12):~~
~~10 mg per lamp~~
~~*Expired on April 13, 2012*~~

2b2 Non-linear halophosphate lamps (all diameters): 15 mg per lamp
Expires on April 13, 2016

2b3 Non-linear tri-band phosphor lamps with tube diameter > 17 mm (T9)
No limitation of use until December 31, 2011.
After December 31, 2011: 15 mg per lamp

2b4 Lamps for other general lighting and special purposes (induction lamps)
No limitation of use until December 31, 2011.
After December 31, 2011: 15 mg per lamp

3 MERCURY in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes not exceeding:

3a Short length (≤ 500 mm). *No limitation of use until December 31, 2011.*
After December 31, 2011: 3.5 mg per lamp

3b Medium length (> 500 mm and ≤ 1,500 mm). *No limitation of use until December 31, 2011.*
After December 31, 2011: 5 mg per lamp

3c Long length (> 1 500 mm). *No limitation of use until December 31, 2011.*
After December 31, 2011: 13 mg per lamp

4a MERCURY in other low pressure discharge lamps. *No limitation of use until December 31, 2011.*
After December 31, 2011: 15 mg per lamp

4b MERCURY in high pressure sodium (vapor) lamps for general lighting purposes in lamps with improved color rendering index Ra > 60 not exceeding:

4b-I P ≤ 155 W. *No limitation of use until December 31, 2011.*
After December 31, 2011: 30 mg per burner

4b-II 155 W < P ≤ 405 W. *No limitation of use until December 31, 2011*
After December 31, 2011: 40 mg per burner

4b-III P > 405 W. *No limitation of use until December 31, 2011.*
After December 31, 2011: 40 mg per burner

4c MERCURY in other high pressure sodium (vapor) lamps for general lighting purposes not exceeding:

4c-I P ≤ 155 W. *No limitation of use until December 31, 2011.*
After December 31, 2011: 25 mg per burner

4c-II 155 W < P ≤ 405 W. *No limitation of use until December 31, 2011.*
After December 31, 2011: 30 mg per burner

4c-III P > 405 W. *No limitation of use until December 31, 2011.*
After December 31, 2011: 40 mg per burner

4d MERCURY in high pressure mercury (vapor) lamps (HPMV)
Expires on April 13, 2015

4e MERCURY in metal halide lamps (MH)

4f MERCURY in other discharge lamps for special purposes not specifically mentioned in this *Annex*

5a LEAD in glass of cathode ray tubes

5b LEAD in glass of fluorescent tubes not exceeding 0.2 % by weight

6a LEAD as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35 % lead by weight

6b LEAD as an alloying element in aluminum containing up to 0.4 % lead by weight

6c Copper alloy containing up to 4 % LEAD by weight

7a LEAD in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

7b LEAD in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications

7c-I Electrical and electronic components containing LEAD in a glass or ceramic other than dielectric ceramic in capacitors (piezoelectronic devices) or in a glass or ceramic matrix compound

7c-II LEAD in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher

7c-III LEAD in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC. *Expires on January 1, 2013*
May be used in spare parts for EEE placed on market before Jan 1, 2013.

7c-IV LEAD in PZT-based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors

8a CADMIUM and its compounds in one shot pellet type thermal cut-offs
Expired January 1, 2012
May be used in spare parts for EEE placed on market before Jan 1, 2012.

8b CADMIUM and its compounds in electrical contacts

9 Hexavalent CHROMIUM as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0.75 % by weight in the cooling solution

9b LEAD in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications

11a LEAD used in C-press compliant pin connector systems

Expired September 24, 2010
May be used in spare parts for EEE placed on market before Sept 24, 2010.

11b LEAD used in other than C-press compliant pin connector systems
Expires on January 1, 2013
May be used in spare parts for EEE placed on market before Jan 1, 2013.

12 LEAD as a coating material for the thermal conduction module C-ring
Expired September 24, 2010
May be used in spare parts for EEE placed on market before Sept 24, 2010.

13a LEAD in white glasses used for optical applications

13b CADMIUM and LEAD in filter glasses and glasses used for reflectance standards

14 LEAD in solders consisting of more than two elements for the connection between pins and package of microprocessors with lead content of more than 80% and less than 85% by weight. *Expired January 1, 2011*
(except spare parts for EEE placed on market before Jan 1, 2011)

15 LEAD in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

16 LEAD in linear incandescent lamps with silicate coated tubes
Expires on September 1, 2013

17 LEAD halide as radiant agent in high intensity discharge (HID) lamps
used for professional reprography applications

18a ~~LEAD as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as specialty lamps for diazoprinting reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS. *Expired January 1, 2011*~~

18b LEAD as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP

19 ~~LEAD with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact energy saving lamps (ESL). *Expired June 1, 2011*~~

20 ~~LEAD oxide in glass used for bonding front & rear substrates of flat fluorescent lamps used for liquid crystal displays (LCD). *Expired June 1, 2011*~~

21 LEAD and CADMIUM in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses

23 LEAD in finishes of fine pitch components other than connectors
with a pitch of 0.65 mm and less. *Expired September 24, 2010*
May be used in spare parts for EEE placed on market before Sept 24, 2010.

24 LEAD in solders for the soldering to machined through hole discoidal or planar array ceramic multilayer capacitors

25 LEAD oxide in surface conduction electron emitter displays (SED) used in structural elements, notably in the seal frit and frit ring

26 ~~LEAD oxide in the glass envelope of black light blue lamps~~
~~*Expired June 1, 2011*~~

27 ~~LEAD alloys as solder for transducers used in high-powered loudspeakers designated to operate for several hours at acoustic power levels of 125 dB SPL and above. *Expired September 24, 2010*~~

29 LEAD bound in crystal glass as defined in *Annex I* (Categories 1, 2, 3, 4) of *Directive 69/493/EEC*

30 CADMIUM alloys as electrical/mechanical solder joints to electrical conductors located directly on the voice coil in transducers used in high-powered loudspeakers with sound pressure levels of 100 dB (A) and more

31 LEAD in soldering materials in mercury free flat fluorescent lamps (used for liquid crystal displays, design or industrial lighting)

32 LEAD oxide in seal frit used for making window assemblies for Argon and Krypton laser tubes

33 LEAD in solders for the soldering of thin copper wires of 100 µm diameter and less in power transformers

34 LEAD in cermet-based trimmer potentiometer elements

36 ~~MERCURY used as a cathode sputtering inhibitor in DC plasma displays with a content up to 30 mg per display. *Expired July 1, 2010*~~

37 LEAD in the plating layer of high voltage diodes on the basis of a zinc borate glass body

38 CADMIUM and cadmium oxide in thick film pastes used on aluminum bonded beryllium oxide

39 CADMIUM in color converting II-VI LEDs (< 10 µg Cd per mm^2 of light-emitting area) for use in solid state illumination or display systems
Expires on July 1, 2014

40 CADMIUM in photoresistors for analogue optocouplers applied in professional audio equipment. *Expires on Dec 31, 2013*

OTHER (Please identify) _____